

RELIABILITY DATA SUMMARY



ON Semiconductor®

Die Related Grand Summary Data

Activation Energy	0.7 eV
Die Junction Temperature	55 °C
One-Sided Upper Confidence Level	90%

Technology	Rejected Devices	Sample Size	Device-Hours	Equivalent Device-Hours	FIT Rate
BiDCMOS	0	10,742	8,472,096	1,971,949,144	1.17
BP STD LINEAR	1	39,143	34,326,704	7,489,074,162	0.52
BPT	2	8,062	6,875,296	1,908,807,984	2.79
CMOS STD	3	24,542	12,980,640	1,935,762,361	3.45
CMOS SUB	2	38,470	27,768,612	3,447,180,924	1.54
HD3e	0	11,744	14,485,296	7,874,903,778	0.29
HVFET	11	20,019	19,635,088	6,763,575,806	2.45
I3T	0	20,339	5,141,448	1,196,128,563	1.93
IGN IGBT	20	27,064	22,882,220	9,831,418,613	2.75
JMOS	0	132	132,000	34,153,317	67.42
MOSAIC	0	2,019	2,138,832	476,668,904	4.83
ONC18	0	31,725	27,453,032	3,834,236,046	0.60
ONC25	6	87,480	59,443,322	7,453,965,185	1.41
RECT	0	44,124	42,954,520	12,458,862,528	0.18
SSD	3	30,902	29,949,960	6,817,139,330	0.98
SST	0	23,048	18,841,344	4,766,759,490	0.48
TMOS 7	0	9,464	9,472,512	5,662,727,158	0.41
TMOS STD	0	15,733	18,352,368	7,724,890,224	0.30
TRENCH	5	31,137	29,154,174	11,293,886,367	0.82
TRENCH SUB	0	70,140	68,897,372	30,799,663,894	0.07
VHVIC	2	27,730	17,588,392	2,244,206,251	2.37
ZENER	1	43,633	45,183,408	10,237,082,350	0.38